

ENGIS[®] MICROTECH HORIZONTAL GRINDING SYSTEM

This unique system is designed to grind Advanced Materials, including wafer backside grinding operations, achieving a high degree of flatness while optimizing surface finishes.

The Model EHG-170-AV Horizontal Grinding Machine is designed for use with Engis diamond wheels which reduce processing times and overall costs.



ADVANCED MATERIALS PRODUCTS

FOR ADDITIONAL INFORMATION CONTACT THE ENGIS MICROTECH TEAM AT

WWW.ENGISCA.COM



MACHINE SPECIFICATIONS

MODEL	EHG - 170 - AV
WHEEL SPEED	4,000 RPM VARIABLE
WORK SPEED	400 RPM, 0.75kW, 200V, 3-PHASE
MAX WORK SIZE	MAX Ø170MM
WHEEL MOTOR	1.5kW, 220V, 3-PHASE
WORK MOTOR	0.75kW, 220V, 3-PHASE
ACCURACY	WITHIN \pm 1UM
WHEEL SIZE	Ø170MM
DIMENSIONS	1,246MM (W) X 650MM (D) X 1,260MM (H)
WEIGHT	1,000KG NET
POWER	220V, 3-PHASE, 50/60HZ, 20A
AIRLINE	6KGF/CM ² (CLEAN & DRY, VACUUM EJECTOR)

OPTIONS

- CHILLER FOR COOLANT TANK
- CARTRIDGE FILTER & FLOW SENSOR SYSTEM
- MAGNETIC CHUCK
- DRESSING FIXTURE
- DIAMOND GRINDING WHEEL Ø170MM

*ENGIS IS ABLE TO DELIVER A COMPLETE SYSTEM TO FIT EACH CUSTOMER'S UNIQUE REQUIREMENTS
AND OPTIMIZE THE MOST DEMANDING APPLICATIONS*

- HYPREZ COMPOSITE LAP PLATES
- DIAMOND AND COLLOIDAL LAPPING & POLISHING SLURRIES
- LUBRICANTS & CLEANERS
- POLISHING PADS/CLOTHS
- WAFER MOUNTING EQUIPMENT
- CONDITIONING RINGS

HGS170-001-0306



3465 Mainway, Unit #2
Burlington, Ontario L7M 1A9
Telephone: 905-632-3016
engiscanada@engis.com
www.engisca.com